PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5842874

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

CONVEYING PARTY DATA

Name	Execution Date
WESTERN ONTARIO COMMUNTY FUTURE DEVELOPMENT CORPORATION ASSOCIATION	11/25/2019

RECEIVING PARTY DATA

Name:	LOST ARROW CONSULTING LLC
Street Address:	665 LYTTON AVE., STE. 6
City:	PALO ALTO
State/Country:	CALIFORNIA
Postal Code:	94301

PROPERTY NUMBERS Total: 8

Property Type	Number
Patent Number:	6946178
Patent Number:	7141348
Patent Number:	7334737
Patent Number:	7335551
Patent Number:	7300824
Patent Number:	7618844
Patent Number:	7863762
Patent Number:	7964964

CORRESPONDENCE DATA

Fax Number: (860)218-9683

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 860-275-6743
Email: smason@mccarter.com
Correspondent Name: SHARON MASON
Address Line 1: 185 ASYLUM STREET
Address Line 2: 36TH FLOOR
Address Line 4: HARTFORD, CONNECTICUT 06103

NAME OF SUBMITTER:	DAVID PENTON
SIGNATURE:	/s/ David Penton

DATE SIGNED:	11/27/2019
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 4
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INTELLECTUAL PROPERTY SECURITY INTEREST RELEASE

This Intellectual Property Security Interest Release (this "Agreement"), dated as of November 25, 2019, is made and entered into by Western Ontario Community Future Development Corporation Association (the "Grantee") in favor of Lost Arrow Consulting LLC, a California limited liability company (the "Grantor"). Except as otherwise defined herein, all capitalized terms used but not defined herein shall have the meanings ascribed to such terms in the IP Security Agreement (defined below).

A. WHEREAS, the Grantor and the Grantee, among others, entered into that certain Loan Agreement dated as of November 6, 2014 (as amended, modified, restated, and/or supplemented from time to time, the "Loan Agreement");

B. WHEREAS, pursuant to the Security Agreement (Intellectual Property) entered into on November 6, 2014 by the Grantor in favor of the Grantee (the "IP Security Agreement"), the Grantor has granted to Grantee a continuing security interest in, and lien on, all of its right, title and interest in, to and under all of its intellectual property, including without limitation, those patents set forth on Exhibit A hereto (collectively, the "IP Collateral");

C. WHEREAS, the IP Security Agreement was recorded at the United States Patent and Trademark Office on November 6, 2014 at Reel 034120, Frame 0352; and

D. WHEREAS, the Grantee wishes to release and restore all right, title and interest in and to the IP Collateral to the Grantor and to dissolve any and all security interests, liens and encumbrances on or relating to the IP Collateral.

NOW, THEREFORE, in consideration of the foregoing, and for other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the Grantee agrees as follows:

1. Termination and Release.

The Grantee, without representation or warranty, hereby (i) releases, discharges, quit claims and relinquishes unto the Grantor its security interest in and lien on any and all right, title and interest in the IP Collateral, (ii) assigns to the Grantor, any right, title, and interest in the IP Collateral that Grantee may possess and (iii) terminates the IP Security Agreement with respect to the IP Collateral

The Grantee will, at any time and from time to time, upon the written request of the Grantor or Terecircuits Corporation (the "Grantor Designee"), at Grantor's expense, promptly execute and deliver any and all further instruments and documents and take such further action as the Grantor may reasonably request to effectuate, evidence or reflect of public record, the release of the security interests and liens referred to in this Agreement.

The Grantee hereby authorizes and requests that the Commissioner for Patents record this Agreement.

2. Miscellaneous

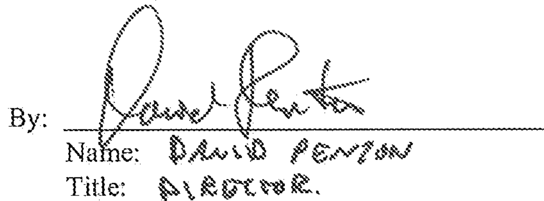
(a) THIS AGREEMENT SHALL BE GOVERNED BY THE LAWS OF THE STATE OF NEW YORK, WITHOUT GIVING EFFECT TO ANY CONFLICT OF LAW PRINCIPLES THAT WOULD RESULT IN THE APPLICATION OF THE LAWS OF ANY OTHER STATE.

(b) This Agreement may be executed in one or more counterparts, each of which shall be deemed an original but all of which shall constitute one and the same instrument.

[SIGNATURE TO FOLLOW]

IN WITNESS WHEREOF, the undersigned has caused this Intellectual Property Security Interest Release to be duly executed and delivered as of the date first written above.

WESTERN ONTARIO COMMUNITY FUTURES
DEVELOPMENT CORPORATION ASSOCIATION, as Grantee



By: ______________________________
Name: DAVID PENTON
Title: DIRECTOR.

EXHIBIT A

Patent Properties

Patent #	Date filed	Date granted	Appl. #	Pub. #	Pub. date	Title
6,946,178	05/23/03	20 Sep 2005	10/444,219	20040234717	11/25/04	Lamination and delamination technique for thin film processing
7,141,348	05/23/03	28 Sep 2005	10/444,435	20040232943	11/25/04	Lamination and delamination technique for thin film processing
	[illegible]	Abandoned	[illegible]	[illegible]	[illegible]	[illegible]
	[illegible]	Abandoned	[illegible]	[illegible]		[illegible]
7,334,737	01/13/05	26 Feb 2008	11/034,634	20060151616	07/13/06	Thin film non volatile memory device scalable to small sizes
7,335,551	01/13/05	26 Feb 2008	11/034,637	20060152960	07/13/06	Method to fabricate a thin film non volatile memory device scalable to small sizes
7,300,824	08/18/05	27 Nov 2007	11/206,606	20070040258	02/22/07	Method of packaging and interconnection of integrated circuits
7,618,844	08/18/05	17 Nov 2009	11/206,605	20070040272	02/22/07	Method of packaging and interconnection of integrated circuits
7,863,762	10/19/07	17 Aug 2009	11/874,907	20080036066	02/14/08	Method of packaging and interconnection of integrated circuits
7,964,964	10/21/09	21 Jun 2011	12/582,940	20100038770	02/18/10	Method of packaging and interconnection of integrated circuits